

Appl. No. 10/774,549  
Amdt. Dated June 23, 2006  
Reply to Office Action of March 23, 2006

Attorney Docket No. 81716.0119  
Customer No. 26021

**REMARKS/ARGUMENTS:**

Claim 2 is amended. Claims 2, 5, 6, 8, and 16 are pending in the application. Reexamination and reconsideration of the application, as amended, are respectfully requested.

The present invention relates to a ceramic circuit board which is constructed by a ceramic substrate and metal circuit plates attached to both surfaces of the ceramic substrate. The invention also relates to a ceramic circuit board which is constructed by a ceramic substrate, metal circuit plates attached to both surfaces of the ceramic substrate, and a metal column arranged within the ceramic substrate to connect the two metal circuit plates, and to a method for manufacturing said ceramic circuit board. (Applicant's specification, at p. 1, lines 5-13).

**CLAIM REJECTIONS UNDER 35 U.S.C. § 112:**

Claim 2 stands rejected under 35 U.S.C. § 112, first paragraph, as failing to comply with the written description and enablement requirements. The Applicant respectfully traverses this rejection.

The Office states that "a cavity is defined along the entire length of the metal column" in claim 2 is not supported or enabled by the Applicant's original disclosure. The Applicant respectfully disagrees.

Claim 2 is both supported and enabled at p. 20, lines 3-24 of the Applicant's specification and in Figures 2A-2C. Figure 2B reveals a cavity that is between the inner wall surface of the through hole 4 and outer wall surface of the metal column 5. According to Figure 2B, the cavity extends along the entire length of the metal column. However, in order to expedite the prosecution of the instant application, the Applicant deleted the phrase "defined along the entire length of the metal column" from claim 2. Withdrawal of this rejection is thus respectfully requested.

Appl. No. 10/774,549  
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CLAIM REJECTIONS UNDER 35 U.S.C. § 103:

Claims 2, 5, 6, 8, and 16 stand rejected under 35 U.S.C. § 103(a) as being unpatentable over Makoto et al. (Japanese Patent No. JP406120634A). The Applicant respectfully traverses this rejection. Claim 2, as amended, is as follows:

A method for manufacturing a ceramic circuit board, comprising the steps of:

preparing a ceramic substrate having a through hole, a metal column with brazing material, and at least two pieces of metal circuit plates, said metal column with brazing material being made longer relative to a thickness of the ceramic substrate, by coating both ends of a metal column which is shorter relative to the thickness of the ceramic substrate, with a brazing material;

arranging the metal column with brazing material within the through hole of the ceramic substrate, so that a space defining a cavity is secured between an inner wall surface of the through hole and an outer wall surface of the metal column, and arranging the metal circuit plates on both surfaces of the ceramic substrate in such a way as to stop up the through hole, wherein the cavity is free from material; and

bonding, after melting the brazing material by heating, the metal column and the metal circuit plates together via the molten brazing material.

Applicant respectfully submits that Makoto cannot render claim 2 obvious because Makoto fails to teach or suggest that a space defining a cavity is secured between an inner wall surface of the through hole and an outer wall surface of the metal column, wherein the cavity is free from material.

Appl. No. 10/774,549

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The Office states,

"In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., 'the space is not filled with the brazing material' p. 6, lines 4-5) are not recited in the rejected claim(s)"

In response, claim 2 was further amended to clarify that the cavity is free of material. It is an aspect of the present invention that the space that defines a cavity offers the advantage that thermal expansion between the ceramic substrate and the metal column is accommodated. (Applicant's specification, at p. 24, lines 20-21). "Thus, even if, when heat is applied to the ceramic circuit board, the outer wall surface of the metal column is expanded and swollen due to the difference in the thermal expansion coefficient between the ceramic substrate and the metal column, the resultant expansion can be successfully accommodated by the space. This helps prevent the inner wall surface of the through hole from being pressed and expanded by the outer wall surface of the metal column, and thereby prevent occurrence of crack or fracture in the ceramic substrate. As a result, the ceramic circuit board can be operated normally and stably for a longer period of time." (Applicant's specification, at p. 12, lines 14-23).

In Makoto, a space is also formed between an inner wall surface of a through hole and an outer wall surface of a pin. However, in Makoto, the melted brazing material enters the space and is filled with a solidified brazing material, as shown in Figures 1(E) and 3(B) of Makoto. In Makoto, "the through hole 12 is filled with solidified brazing metal 18 thus ensuring conduction between the aluminum plates 14, 16 on the surface and the rear." (Makoto, Abstract- English translation, at p. 2, lines 13-17). On the other hand, in the present invention, the space is not filled with the brazing material. When the space is filled with the brazing material, it is

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difficult for the space to securely accommodate the expansion of the inner wall surface of the through hole of the substrate, which is caused by the outer wall surface of the metal column swollen. Makoto does not consider this point. In the present invention, the brazing material (items 2 and 6 of Figure 1) is restricted to the upper and lower surfaces of the ceramic substrate and the ends of the metal column. (Applicant's specification, at p. 16, lines 13-19). Hence, the space between the metal column and the ceramic substrate defines a cavity, and the benefits discussed above are achieved.

In light of the foregoing, Applicant respectfully submits that Makoto could not have rendered claim 2 obvious, because Makoto fails to teach or suggest each and every claim limitation. Claims 5, 6, 8, and 16 depend from claim 2 and cannot be rendered obvious for at least the same reasons as claim 2. Withdrawal of these rejections is thus respectfully requested.

Applicant believes the foregoing amendments comply with requirements of form and thus may be admitted under 37 C.F.R. § 1.116(b). Alternatively, if these amendments are deemed to touch the merits, admission is requested under 37 C.F.R. § 1.116(c). In this connection, these amendments were not earlier presented because they are in response to the matters pointed out for the first time in the Final Office Action.

Lastly, admission is requested under 37 C.F.R. § 1.116(b) as presenting rejected claims in better form for consideration on appeal.

In view of the foregoing, it is respectfully submitted that the application is in condition for allowance. Reexamination and reconsideration of the application, as amended, are requested.

If for any reason the Examiner finds the application other than in condition for allowance, the Examiner is requested to call the undersigned attorney at the Los

Appl. No. 10/774,549  
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Attorney Docket No. 81716.0119  
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Angeles, California telephone number (213) 337-6700 to discuss the steps necessary for placing the application in condition for allowance.

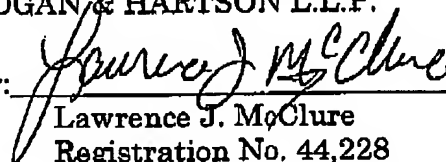
If there are any fees due in connection with the filing of this response, please charge the fees to our Deposit Account No. 50-1314.

Respectfully submitted,

HOGAN & HARTSON L.L.P.

Date June 23, 2006

By:



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